

## Listing of Claims

### Claims 1-20 (Canceled)

21. (withdrawn) A method for testing a semiconductor component having a plurality of terminal contacts comprising:

    providing a board comprising a plurality of contacts in electrical communication with test circuitry;

    providing a substrate on the board;

    providing a plurality of movable test contactors on the substrate comprising first contacts including conductive polymer layers configured to electrically engage the terminal contacts and second contacts including conductive polymer layers in electrical communication with the first contacts and configured to electrically engage the contacts;

    placing the component on the substrate with the terminal contacts in electrical communication with the first contacts and the second contacts in electrical communication with the contacts; and

    applying test signals through the test contactors and the terminal contacts to the component.

22. (withdrawn) The method of claim 21 wherein the substrate comprises a plurality of grooves separating the contactors and forming flexible segments for the contactors.

23. (withdrawn) The method of claim 21 further comprising applying a force to the component during the placing step.

24. (withdrawn) The method of claim 21 wherein the substrate is configured to float on the board.

25. (withdrawn) The method of claim 21 wherein the terminal contacts comprise an element selected from the group consisting of leads, bumps and pads.

26. (withdrawn) The method of claim 21 wherein the placing step is performed using a test handler.

27. (withdrawn) A method for testing a semiconductor component having a terminal contact comprising:

providing a board comprising at least one contact in electrical communication with test circuitry;

providing a substrate on the board comprising at least one contactor configured to simultaneously electrically engage the contact and the terminal contact, the contactor comprising a first conductive polymer layer on a first side of the substrate configured to electrically engage the terminal contact, and a second conductive polymer layer on a second opposing side of the substrate in electrical communication with the first conductive polymer layer configured to electrically engage the contact;

placing the component on the board with the first conductive polymer layer in electrical communication with the terminal contact and the second conductive polymer layer in electrical communication with the contact; and

applying test signals through the terminal contact, the contact, the second conductive polymer layer, and the first conductive polymer layer to the component.

28. (withdrawn) The method of claim 27 wherein the substrate is configured to float in a Z-direction on the board,

29. (withdrawn) The method of claim 27 wherein the substrate comprises grooves on either side of the contactor

electrically isolating the contactor and forming a flexible segment on the substrate for the contactor.

30. (withdrawn) The method of claim 27 wherein the terminal contact comprises an element selected from the group consisting of leads, bumps and pads.

31. (withdrawn) The method of claim 27 wherein the component comprises an element selected from the group consisting of packages, BGA devices and modules.

32. (withdrawn) A method for testing a semiconductor component having a plurality of terminal contacts comprising:

providing a board comprising a plurality of contacts in electrical communication with test circuitry;

providing a floating substrate on the board;

providing a plurality of test contactors on the substrate, each test contactor comprising a flexible segment on the substrate, a first conductive polymer layer on a first side of the flexible segment configured to electrically engage a terminal contact, and a second conductive polymer layer on a second opposing side of the flexible segment in electrical communication with the first conductive polymer layer and configured to electrically engage a contact on the board;

placing the component on the substrate with the terminal contacts in electrical communication with the test contactors; and

applying test signals through the test contactors and the terminal contacts to the component.

33. (withdrawn) The method of claim 32 wherein the test contactors comprise an element selected from the group consisting of gold and platinum.

34. (withdrawn) The method of claim 32 wherein the first conductive polymer layer and the second conductive polymer layer comprise an elastomeric base material and a plurality of conductive particles in the base material.

35. (withdrawn) The method of claim 32 wherein the flexible segments allow the test contactors to move independently to accommodate dimensional variations in the terminal contacts.

36. (withdrawn) The method of claim 32 wherein the terminal contacts comprise leads and the first conductive polymer layer comprises a plurality of conductive particles configured to penetrate a lead.

37. (withdrawn) The method of claim 32 wherein the terminal contacts comprises bumps and the first conductive polymer layer comprises an indentation for engaging a bump.

38. (withdrawn) The method of claim 32 wherein the terminal contacts comprise pads and the first conductive polymer layer comprises a bump for engaging a pad.

39. (withdrawn) The method of claim 32 wherein the placing step is performed using a test handler.

40. (withdrawn) The method of claim 32 wherein the substrate comprises an opening and the board comprises a pin for physically engaging the opening.

41. (currently amended) A contact system for a semiconductor component having a plurality of terminal contacts comprising:

a board comprising a plurality of contacts in electrical communication with external circuitry;

a substrate configured to slide on the board comprising a plurality of flexible segments configured to move independently of one another and a plurality of contactors on the flexible segments configured to simultaneously electrically engage the contacts and the terminal contacts;

each contactor comprising a first contact on a first side of the substrate flexible segment configured to electrically engage a terminal contact on the component, and an anisotropic a conductive polymer layer on a second opposing side of the substrate flexible segment in electrical communication with the first contact configured to electrically engage a contact on the board.

42. (currently amended) The contact system of claim 41 wherein the substrate comprises a plurality of grooves separating the contactors and forming the flexible segments.  
~~for the contactors.~~

43. (previously presented) The contact system of claim 41 further comprising a test handler configured to place and hold the component on the substrate.

44. (currently amended) The contact system of claim 41 wherein the substrate slides in a z-direction on pins attached to the board.  
~~is configured to float on the board.~~

45. (previously presented) The contact system of claim 41 wherein the terminal contacts comprise an element selected from the group consisting of leads, bumps and pads.

46. (previously presented) The contact system of claim 41 wherein the external circuitry comprises test circuitry.

47. (currently amended) A contact system for a semiconductor component having a plurality of terminal contacts comprising:

~~an interface a board comprising at least one a plurality of interface contacts in electrical communication with external circuitry and a plurality of pins;~~

~~a substrate on the board slidably mounted on the pins having a first side and an opposing second side plurality of flexible segments configured to move independently of one another;~~

~~at least one a plurality of contactors on the substrate flexible segments configured to simultaneously electrically engage the interface contacts and the terminal contacts;~~

~~the each contactor comprising a first contact on the a first side of a flexible segment configured to electrically engage the a terminal contact, a second contact on the a second side of the flexible segment in electrical communication with the first contact, and an anisotropic a conductive polymer layer configured to electrically engage the second contact and the a interface contact.~~

48. (currently amended) The contact system of claim 47 wherein the substrate comprises a plurality of grooves on either side of the contactors forming the providing a flexible segments.

~~on the substrate for the contactor.~~

49. (currently amended) The contact system of claim 47 wherein the anisotropic conductive polymer layer comprises an elastomeric base material and a plurality of

conductive particles in the base material configured to electrically engage the ~~interface~~ contact.

50. (previously presented) The contact system of claim 47 wherein the terminal contact comprises a lead and the first contact comprises a pad configured to physically engage the lead.

51. (withdrawn and currently amended) The contact system of claim 47 wherein the terminal contact comprises a bump and the first contact comprises an indentation for the bump.

52. (withdrawn) The contact system of claim 47 wherein the terminal contact comprises a pad and the first contact comprises a bump for engaging the pad.

53. (previously presented) The contact system of claim 47 wherein the component comprises an element selected from the group consisting of packages, ball grid array devices, and modules.

54. (currently amended) A contact system for a semiconductor component having a plurality of terminal contacts comprising:

~~an interface a board comprising a plurality of interface contacts in electrical communication with an external circuitry;~~

~~a substrate on slidably mounted to the interface board for movement in a z-direction and having a first side, an opposing second side, and a plurality of grooves from the first side to the second side forming a plurality of flexible segments;~~

~~a plurality of contactors on the flexible segments configured to move independently of one another and to~~

simultaneously electrically engage the interface contacts and the terminal contacts;

each contactor comprising a first contact on the first side of a flexible segment configured to electrically engage the terminal contact, a second contact on the second side of the flexible segment in electrical communication with the first contact, and an anisotropic a conductive polymer layer configured to electrically engaging engage the second contact and an interface a contact.

55. (previously presented) The contact system of claim 54 wherein the first contact and the second contact comprise an element selected from the group consisting of gold and platinum.

56. (currently amended) The contact system of claim 54 wherein the anisotropic conductive polymer layer comprises an elastomeric base material and a plurality of conductive particles in the base material.

57. (currently amended) The contact system of claim 54 wherein the conductive polymer layer comprises a plurality of particles configured to penetrate the second contacts.

~~flexible segments allow the contactors to move independently to accommodate dimensional variations in the terminal contacts.~~

58. (currently amended) A contact system for a semiconductor component having a plurality of terminal contacts comprising:

a test circuitry configured to apply test signals to the component;

a test handler configured to move and support the component;

a board comprising a plurality of contacts in electrical communication with the test circuitry;

a substrate on the board comprising a plurality of independent flexible segments and a plurality of contactors on the flexible segments configured under a force applied by the test handler to the component to simultaneously electrically engage the contacts and the terminal contacts;

each contactor comprising a first contact on a first side of ~~the substrate~~ a flexible segment configured to electrically engage a terminal contact on the component, and a second contact on a second opposing side of the ~~substrate~~ flexible segment in electrical communication with the first contact, and ~~an anisotropic~~ a conductive polymer layer configured to electrically engage the second contact and a contact on the board.

59. (previously presented) The contact system of claim 58 wherein the substrate is configured to float in a Z-direction on the board,

60. (currently amended) The contact system of claim 58 wherein the substrate comprises a plurality of grooves electrically isolating the contactors and forming the flexible segments,  
~~on the substrate for the contactors.~~

61. (withdrawn) A method for testing a semiconductor component having a plurality of terminal contacts comprising:

providing a board comprising a plurality of contacts in electrical communication with test circuitry;

providing a substrate on the board;

providing a plurality of movable test contactors on the substrate comprising first contacts configured to electrically engage the terminal contacts and second contacts in electrical communication with the first

contacts, and an anisotropic conductive polymer layer proximate to the second side configured to electrically engage second contacts and the contacts;

placing the component on the substrate with the terminal contacts in electrical communication with the first contacts and the second contacts in electrical communication with the contacts; and

applying test signals through the test contactors and the terminal contacts to the component.

62. (withdrawn) The method of claim 61 wherein the substrate comprises a plurality of grooves separating the contactors and forming flexible segments for the contactors.

63. (withdrawn) The method of claim 61 further comprising applying a force to the component during the placing step.

64. (withdrawn) The method of claim 61 wherein the substrate is configured to float on the board.

65. (withdrawn) The method of claim 61 wherein the terminal contacts comprise an element selected from the group consisting of leads, bumps and pads.

66. (withdrawn) The method of claim 61 wherein the placing step is performed using a test handler.

67. (withdrawn) A method for testing a semiconductor component having a terminal contact comprising:

providing a board comprising at least one contact in electrical communication with test circuitry;

providing a substrate on the board comprising at least one contactor configured to simultaneously electrically engage the contact and the terminal contact, the contactor

comprising a first contact on a first side of the substrate configured to electrically engage the terminal contact, a second contact on the second side in electrical communication with the first contact, and an anisotropic conductive polymer layer proximate to a second opposing side of the substrate configured to electrically engage the second contact and the contact;

placing the component on the board with the first contact in electrical communication with the terminal contact and the second contact in electrical communication with the contact; and

applying test signals through the terminal contact, the contact, the second contact, and the anisotropic conductive polymer layer to the component.

68. (withdrawn) The method of claim 67 wherein the substrate is configured to float in a Z-direction on the board,

69. (withdrawn) The method of claim 67 wherein the substrate comprises grooves on either side of the contactor electrically isolating the contactor and forming a flexible segment on the substrate for the contactor.

70. (withdrawn) The method of claim 67 wherein the terminal contact comprises an element selected from the group consisting of leads, bumps and pads.

71. (withdrawn) The method of claim 67 wherein the component comprises an element selected from the group consisting of packages, BGA devices and modules.

72. (withdrawn) A method for testing a semiconductor component having a plurality of terminal contacts comprising:

providing a board comprising a plurality of contacts in electrical communication with test circuitry;

providing a floating substrate on the board;

providing a plurality of test contactors on the substrate, each test contactor comprising a flexible segment on the substrate, a first contact on a first side of the flexible segment configured to electrically engage a terminal contact, a second contact and on a second opposing side of the flexible segment in electrical communication with the first contact, and an anisotropic conductive polymer configured to electrically engage the second contact and a contact on the board;

placing the component on the substrate with the terminal contacts in electrical communication with the test contactors; and

applying test signals through the test contactors and the terminal contacts to the component.

73. (withdrawn) The method of claim 72 wherein the test contactors comprise an element selected from the group consisting of gold and platinum.

74. (withdrawn) The method of claim 72 wherein the first conductive polymer layer and the second conductive polymer layer comprise an elastomeric base material and a plurality of conductive particles in the base material.

75. (withdrawn) The method of claim 72 wherein the flexible segments allow the test contactors to move independently to accommodate dimensional variations in the terminal contacts.

76. (withdrawn) The method of claim 72 wherein the placing step is performed using a test handler.

77. (withdrawn) The method of claim 72 wherein the substrate comprises an opening and the board comprises a pin for physically engaging the opening.